IN THE U

E U.S. PATENT AND TRADEMARK OFFICE

June 25, 2010

Applicants: Katsuyuki TSUCHIDA et al

Title: COPPER ELECTROLYTIC SOLUTION CONTAINING AS ADDITIVE

COMPOUND HAVING SPECIFIC SKELETON, AND

ELECTROLYTIC COPPER FOIL MANUFACTURED THEREWITH

Serial No.: 10/588 686 Group:

Confirmation No.: 9917\

Filed: August 7, 2006 Examiner: Wong

International Application No.: PCT/JP2005/022662

International Filing Date: December 9, 2005

Atty. Docket No.: 4700.P0335US

Mail Stop Amendment

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

## Sir:

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Herewith is an amendment in the above-identified application.

- [] Applicant claims small entity status. See 37 CFR 1.27.
- [] The additional filing fee has been calculated as shown below:

	No.	No.	(X)	RATE	()		
For	Filed	Extra	LG Entity		SM Entity	Fee	:
Total Claims	(3 - 20	= 0)	x \$ 52.00		x \$ 26.00		
Indep. Claims	(1 - 3	= 0)	x \$220.00		x \$110.00		
[] Multiple De	p. Claim		+ \$390.00		+ \$195.00		
* * * TOTAL FILING FEE * * *						\$	0.00

- [] Pursuant to 37 CFR 1.136(a), please extend the shortened period for response by month(s). The extension fee is: \$.
- [] A Check for \$ is enclosed to cover fees.
- [X] Please credit any overpayment, or charge any additional filing fee required under 37 CFR 1.16 or 1.17 by this communication, to Deposit Account No. 06-1382.

TFC/smd

Terryence F. Chapman Reg. No. 32 549

## CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on June 25, 2010.

130.10/08

Terrvence F. Chapman